

ABSTRACT OF THE DISCLOSURE

A test kit for a semiconductor package and a method for testing the semiconductor package using the same are provided. The test kit for a semiconductor package includes a
5 pick-and-place tool for picking up and loading/unloading the semiconductor package, a head assembly having a package guider and a socket guider, and a socket which is positioned under the head assembly. The socket guider performs a pre-alignment function for a correct operation of the package guider, before the package guider starts operating. The package guider aligns the semiconductor package.

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